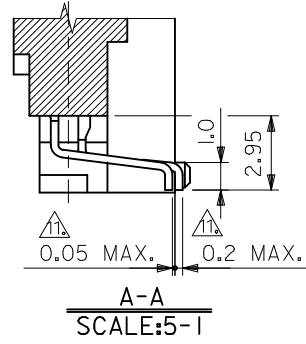
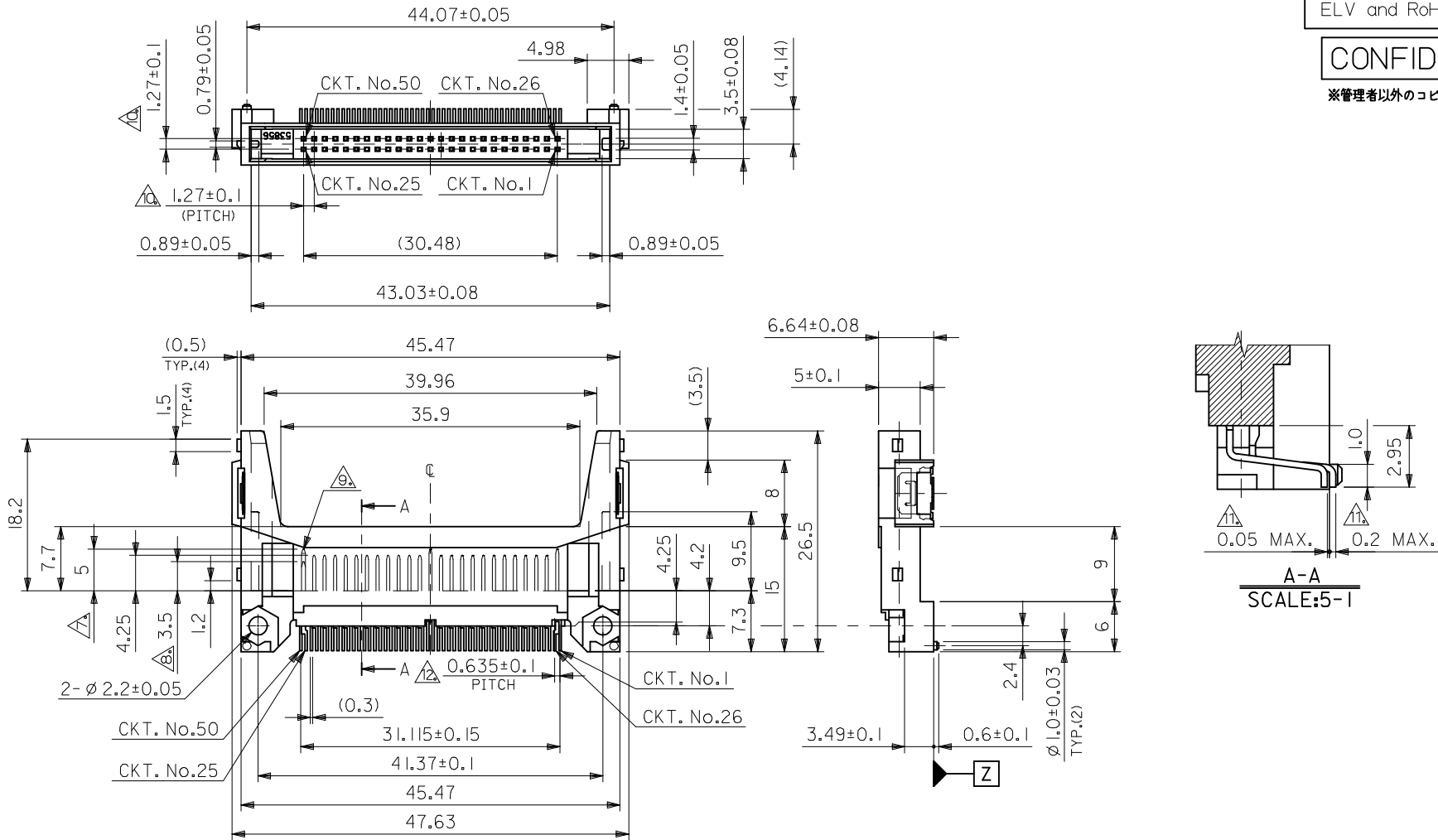


ELV and RoHS Compliant

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※管理者以外のコピー及び配布を禁ずる



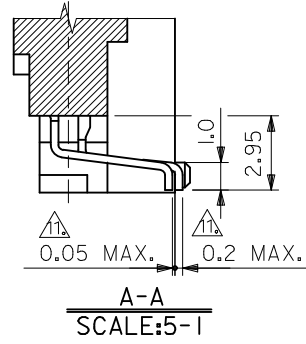
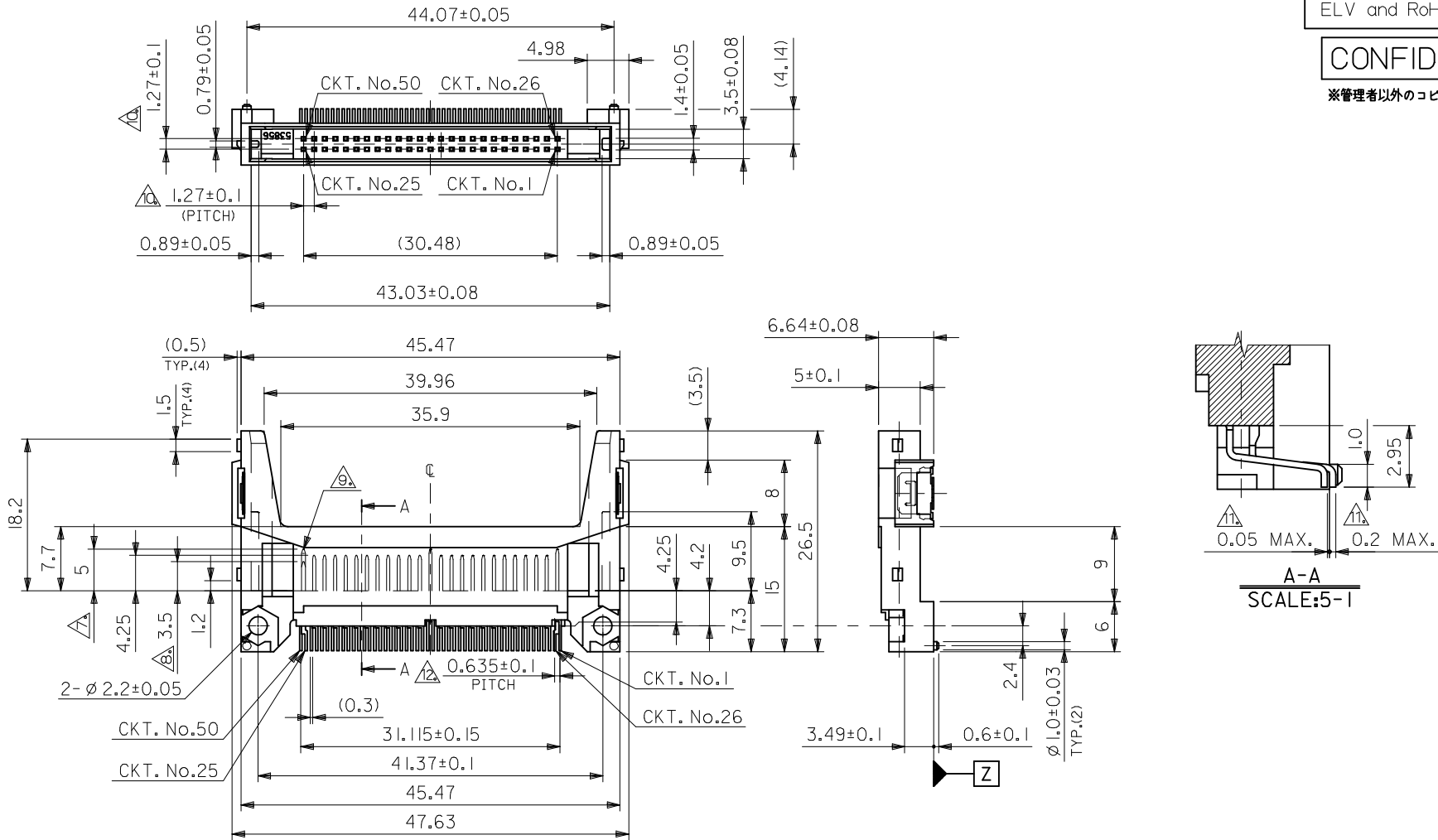
SOFT TRAY PACKAGE	WHITE	53856-5070	50	53856-507*
PACKING TRAY FORM	HOUSING COLOR	MATERIAL No.	No. OF CKT.	MODEL No.

REVISED EC NO: J2017-0575 DRWNGES: 2017/05/19 CHKD: APPR: MSASAO 2017/06/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	0.25 UNDER ±0.03		MM ONLY		---	METRIC	☉
	0.25 OVER	0.5 UNDER ±0.05	DRAWN BY	DATE	TITLE		
	0.5 OVER	1.0 UNDER ±0.1	M. NABEI	'04/03/16	CF CARD CONN. HEADER ASS'Y -LEAD FREE-		
1.0 OVER	10 UNDER ±0.2	CHECKED BY	DATE	molex DOCUMENT NO. SD-53856-007 SHEET NO. 1 OF 2			
10 OVER	30 UNDER ±0.25	K. TOJO	'04/03/16				
30 OVER	±0.3	APPROVED BY	DATE	SEE CHART THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
ANGULAR	±3 °	M. SASAO	'04/03/16				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE					
		A3					

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SOFT TRAY PACKAGE	WHITE	53856-5070	50	53856-507*
PACKING TRAY FORM	HOUSING COLOR	MATERIAL No.	No. OF CKT.	MODEL No.

REVISED EC NO: J2017-0575 DRWNGES: 2017/05/19 CHKD: APPR: MSASAO 2017/06/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	0.25 UNDER ±0.03		MM ONLY		---	METRIC	☉
	0.25 OVER	0.5 UNDER ±0.05	DRAWN BY	DATE	TITLE		
	0.5 OVER	1.0 UNDER ±0.1	M. NABEI	'04/03/16	CF CARD CONN. HEADER ASS'Y -LEAD FREE-		
1.0 OVER	10 UNDER ±0.2	CHECKED BY	DATE	molex DOCUMENT NO. SD-53856-007 SHEET NO. 1 OF 2			
10 OVER	30 UNDER ±0.25	K. TOJO	'04/03/16				
30 OVER	±0.3	APPROVED BY	DATE	SEE CHART THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
ANGULAR	±3 °	M. SASAO	'04/03/16				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE					
		A3					

注) NOTES

- 材質
MATERIAL
ハウジング: ガラス入りLCP UL94V-0
HOUSING: LCP G.F. UL94V-0
ピン: リン青銅
PIN: PHOSPHOR BRONZE
ネール: リン青銅
NAIL: PHOSPHOR BRONZE
- メッキ仕様
PLATING
PIN 接点部: ニッケル下地, パラジウムニッケル, 金メッキ
CONTACT AREA: PALLADIUM-NICKEL, GOLD OVER NICKEL
半田付け部: 錫メッキ
SOLDER TAIL AREA: TIN
下地メッキ: ニッケルメッキ
UNDERPLATING: NICKEL OVER ALL
NAIL 錫メッキ
TIN
下地メッキ: ニッケルメッキ
UNDERPLATING: NICKEL OVER ALL

3. 推奨基板厚: $t \geq 0.8$ MIN.
RECOMMENDED P.C.B. THICKNESS: $t \geq 0.8$ MIN.

4. 適合カード厚
RECOMMENDED CARD THICKNESS
接続部: 3.3 ± 0.1
CONNECTING AREA: 3.3 ± 0.1

5. 適合カード幅: 42.8 ± 0.1
RECOMMENDED CARD WIDTH: 42.8 ± 0.1

6. ハウジング色:
HOUSING COLOR:
53856-5010: 白 (WHITE)
53856-5010: 黒 (BLACK)

△寸 1,13,38,50
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS
1,13,38 AND 50.

△寸 25,26
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.

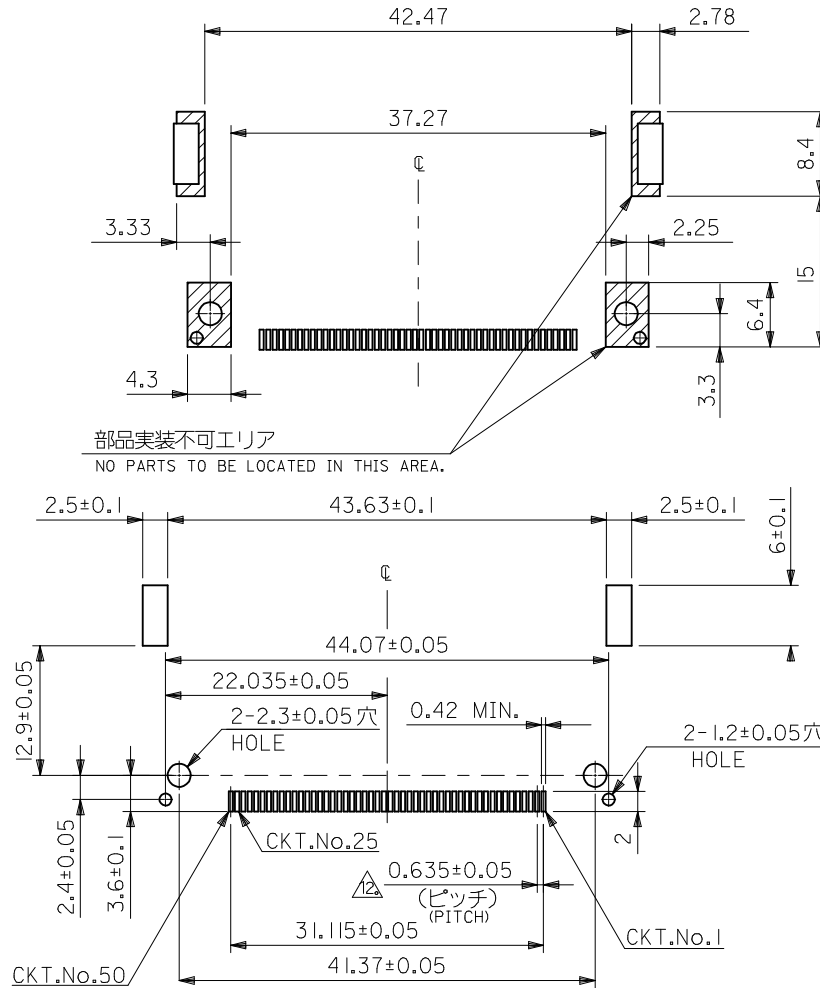
△ピンのはれは、ピン根元を基準に全方向へ0.1 MAX.とする。
PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1
WHEN MEASURED FROM PIN BASE.

△ピン根元に適用する。
THIS DIMENSION TO BE MEASURED AT PIN BASE.

△ソルダーテールは、Z面を基準とし上へ0.05下へ0.2の範囲にあり、
目付ソルダーテールの平坦度は、0.15 MAX.とし、テール先端にて測定する。
SOLDERTAILS TO BE WITHIN 0.05 UPWARD AND 0.2 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY
OF SOLDERTAILS TO BE WITHIN 0.15.
MEASUREMENT POINT IS SOLDERTAILS TIP.

△公差非累積
NON-CUMULATIVE

13. 本製品は 53856-501* の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53856-501*.



基板推奨寸法
RECOMMENDED P.C.B. LAYOUT

REVISED EC NO: J2017-0575 DRWNGES 2017/05/19	CHKD: APPR:MSASAO 2017/06/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		0.25 UNDER	±0.03	DRAWN BY M. NABEI	DATE '04/03/16	TITLE CF CARD CONN. HEADER ASS'Y -LEAD FREE-		
REV B	DESCRIPTION	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY K. TOJO	DATE '04/03/16	DOCUMENT NO. SD-53856-007	
		0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M. SASAO	DATE '04/03/16		
		1.0 OVER	10 UNDER	±0.2	MATERIAL NO.			
		10 OVER	30 UNDER	±0.25	SEE SHEET1			
		30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

注) NOTES

- 材質
MATERIAL
ハウジング: ガラス入りLCP UL94V-0
HOUSING: LCP G.F. UL94V-0
ピン: リン青銅
PIN: PHOSPHOR BRONZE
ネール: リン青銅
NAIL: PHOSPHOR BRONZE
- メッキ仕様
PLATING
PIN 接点部: ニッケル下地, パラジウムニッケル, 金メッキ
CONTACT AREA: PALLADIUM-NICKEL, GOLD OVER NICKEL
半田付け部: 錫メッキ
SOLDER TAIL AREA: TIN
下地メッキ: ニッケルメッキ
UNDERPLATING: NICKEL OVER ALL
NAIL 錫メッキ
TIN
下地メッキ: ニッケルメッキ
UNDERPLATING: NICKEL OVER ALL

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4. 適合カード厚
RECOMMENDED CARD THICKNESS
接続部: 3.3 ± 0.1
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1,13,38 AND 50.

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THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.

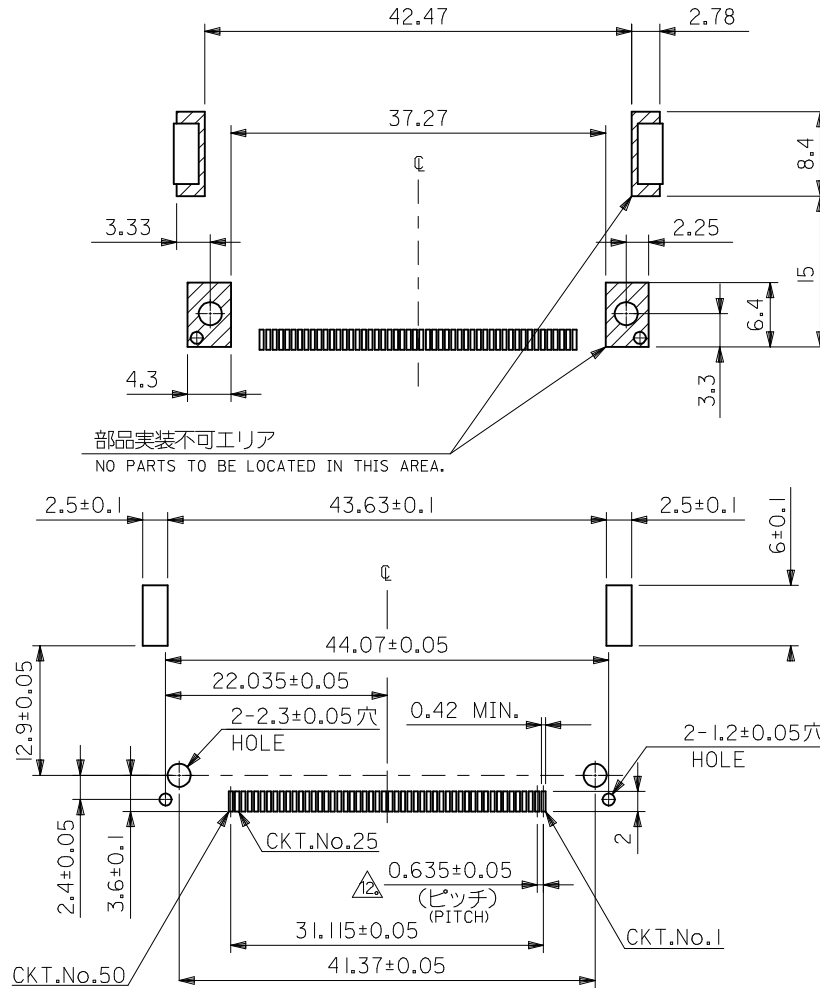
△ピンのはれは、ピン根元を基準に全方向へ0.1 MAX.とする。
PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1
WHEN MEASURED FROM PIN BASE.

△ピン根元に適用する。
THIS DIMENSION TO BE MEASURED AT PIN BASE.

△ソルダータールは、Z面を基準とし上へ0.05下へ0.2の範囲にあり、
目付ソルダータールの平坦度は、0.15 MAX.とし、テール先端にて測定する。
SOLDERTAILS TO BE WITHIN 0.05 UPWARD AND 0.2 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY
OF SOLDERTAILS TO BE WITHIN 0.15.
MEASUREMENT POINT IS SOLDERTAILS TIP.

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NON-CUMULATIVE

13. 本製品は 53856-501* の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53856-501*.



基板推奨寸法
RECOMMENDED P.C.B. LAYOUT

REVISED EC NO: J2017-0575 DRAWINGS 2017/05/19 CHKD: APPR:MSASAO 2017/06/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±0.03	DRAWN BY M.NABEI	DATE '04/03/16	TITLE CF CARD CONN. HEADER ASS'Y -LEAD FREE-		
0.25 OVER	0.5 UNDER	±0.05	CHECKED BY K.TOJO	DATE '04/03/16	DOCUMENT NO. molex SD-53856-007		
0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M.SASAO	DATE '04/03/16			
1.0 OVER	10 UNDER	±0.2	MATERIAL NO.	SEE SHEET1			
10 OVER	30 UNDER	±0.25	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	SHEET NO. 2 OF 2	
30 OVER	±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					